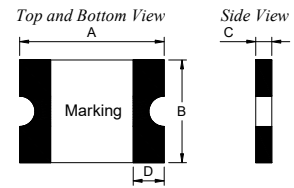


### 1、 Physical Dimensions(size of 2920)

Unit:mm

Part Number	A		B		C		D	Marking
	Min	Max	Min	Max	Min	Max	Min	
KLSMD300/33	6.73	7.98	4.80	5.44	0.70	1.40	0.30	T300



### 2、 Electrical Characteristics

Part Number	I <sub>H</sub> (A)	I <sub>T</sub> (A)	V <sub>max</sub> (V)	I <sub>max</sub> (A)	T <sub>trip</sub> (Max time to trip)		Pd <sub>typ</sub> (W)	R <sub>min</sub> (Ω)	R1 <sub>max</sub> (Ω)
					Current(A)	Time(S)			
KLSMD300/33	3.00	6.00	33	40	8.0	25	1.5	0.010	0.055

I<sub>H</sub>: Holding Current: maximum current at which the device will not trip in 25°C still air.

I<sub>T</sub>: Tripping Current minimum current at which the device will trip in 25°C still air.

V<sub>max</sub>: Maximum voltage device can withstand without damage at rated current.

I<sub>max</sub>: Maximum fault current device can withstand without damage at rated voltage.

T<sub>trip</sub>: Maximum time to trip(s) at assigned current.

Pd<sub>typ</sub>: Rated working power.

R<sub>min</sub>: Minimum resistance of device prior to trip at 25°C.

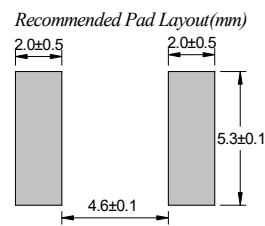
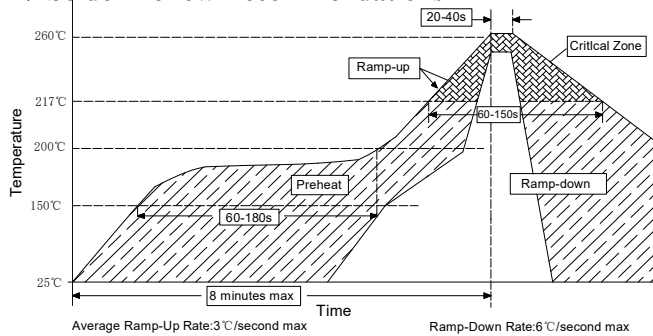
R1<sub>max</sub>: Maximum resistance of device is measured one hours post reflow at 25°C.

Noted: All electrical function test is conducted after PCB mounted.

### 3、 Thermal Derating

KLSMD300/33	Maximum ambient operating temperature								
	-40°C	-20°C	0°C	25°C	40°C	50°C	60°C	70°C	85°C
Hold Current(A)	4.53	4.02	3.51	3.00	2.52	2.26	1.99	1.75	1.34
Trip Current(A)	9.06	8.04	7.02	6.00	5.04	4.52	3.98	3.50	2.68

### 4、 Solder Reflow Recommendations



Notes: If reflow temperatures exceed the recommended profile, devices may not meet the performance requirements.

### 5、 Package Information

Packing quantity: 1000PCS/Reel

Note: Reel packaging per EIA-481-2 standard